

PRESSURIZED LIQUID DELIVERY MODULE**ABSTRACT OF THE DISCLOSURE**

5 A pressurized delivery module having two chambers enables refill of the module while liquid material continues to be supplied to a semiconductor processing tool. Initially, the chambers are in fluid communication with each other through a valve assembly, with positive pressure applied to the module from an inert gas supply. When material in the module becomes depleted, the chambers are isolated from one another to permit refilling. In the refill module state, one chamber remains pressurized, 10 with material remaining therein continued to be dispensed to the semiconductor fabrication tool. The second chamber is vented and placed into fluid communication with the bulk material supply. Once the level of material in the second chamber has been replenished and processing of the remaining wafer has been completed, during transfer of the next incoming wafer to the tool, the second chamber is sealed off from 15 the material supply, repressurized, and placed back into fluid communication with the first chamber.

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